

XA-9890 PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Takashi MIWA et al.

Appln. No.: 10/606,891

Group Art Unit: 2824

Filed: June 27, 2003

Examiner: A. Tran

For: STACKED LARGE-SCALE INTEGRATED CIRCUIT (LSI) SEMICONDUCTOR DEVICE WITH MINIATURIZATION AND THINNING OF PACKAGE (AS AMENDED)

RESPONSE

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Responsive to the Examiner's request in the Communication dated September 19, 2005, a reformatted version of the substitute specification is submitted herewith. The reformatted version is identical in content to the previously filed version, except that the spelling of "Package" has been corrected in the title.

A further action on the merits is respectfully requested.

The Commissioner is hereby authorized to charge to Deposit Account No. 50-1165 any fees under 37 C.F.R. §§ 1.16 and 1.17 that may be required by this paper and to credit any overpayment to that Account. If any extension of time is required in connection with the filing of this paper and has not been requested separately, such extension is hereby requested.

Respectfully submitted,

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September 28, 2005

By: / 7

Mitchell W. Shapirq

Reg. No. 31,568